Supplier Name:
Contact Info:
Form/Declaration Type:
Created on:

Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - RoHS and IEC 62474 DB

Distribute - RoHS and IE0 05/19/2022

Details for "ISO721MD"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
ISO721MD	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D 8	3.91x4.9x1.58	176.1

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm	
Bond Wire								
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.00065	7	0.000001	0	
Precious Metals	Gold	7440-57-5	0.15373	99.998049	999980	0.087313	873	
Precious Metals	Silver	7440-22-4	0.000002	0.001301	13	0.000001	0	
Sub-Total			0.153733	100	1000000	0.087315	873	
Die Attach Adhesive								
Precious Metals	Silver	7440-22-4	0.112875	75	750000	0.064109	641	
Thermoplastics	Epoxy	85954-11-6	0.037625	25	250000	0.02137	214	
Sub-Total			0.1505	100	1000000	0.085479	855	
Die Attach Adhesive 2								
Precious Metals	Silver	7440-22-4	0.181555	75.000103	750001	0.103117	1031	
Thermoplastics	Epoxy	85954-11-6	0.060518	24.999897	249999	0.034372	344	
Sub-Total			0.242073	100	1000000	0.137489	1375	
Lead Frame								
Copper and Its Alloys	Copper	7440-50-8	113.154477	97.05	970500	64.267869	642679	
Copper and Its Alloys	Iron	7439-89-6	3.031444	2.6	26000	1.721756	17218	
Copper and Its Alloys	Phosphorus	7723-14-0	0.174891	0.15	1500	0.099332	993	
Zinc and Its Alloys	Zinc	7440-66-6	0.233188	0.2	2000	0.132443	1324	
Sub-Total			116.594	100	1000000	66.2214	662214	
Lead Frame Plating								
Nickel and Its Alloys	Nickel	7440-02-0	0.385236	95.12	951200	0.218801	2188	
Precious Metals	Gold	7440-57-5	0.003159	0.78	7800	0.001794	18	
Precious Metals	Palladium	7440-05-3	0.016605	4.1	41000	0.009431	94	
Sub-Total			0.405	100	1000000	0.230026	2300	
Mold Compound								
Other Inorganic Materials	Fused Silica	60676-86-0	49.09366	86	860000	27.883518	278835	
Other Plastics and Rubber	Carbon Black	1333-86-4	0.171257	0.3	3000	0.097268	973	
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.313971	0.55	5500	0.178325	1783	
Thermoplastics	Epoxy	85954-11-6	7.506763	13.15	131500	4.263584	42636	
Sub-Total			57.085651	100	1000000	32.422695	324227	
Semiconductor Device								
Ceramics / Glass	Doped Silicon	7440-21-3	0.550513	100	1000000	0.312673	3127	
Sub-Total			0.550513	100	1000000	0.312673	3127	
Semiconductor Device 2								
Ceramics / Glass	Doped Silicon	7440-21-3	0.88548	100	1000000	0.502922	5029	
Sub-Total			0.88548	100	1000000	0.502922	5029	
							1	
Total			176.06695			100	1000000	

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one Ti part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different Ti part numbers. If this occurs, please check your Customer Part Number and cross reference it with the Ti part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/19/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products are also fully compliant with ADSL and the IEC 6247d database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the ROHS Annex II threshold, but that fall within one of the specific ROHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.